

2MBI150VA-120-50

IGBT Modules

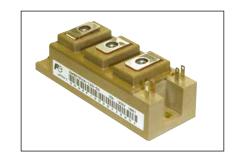
IGBT MODULE (V series) 1200V / 150A / 2 in one package

Features

High speed switching Voltage drive Low Inductance module structure

Applications

Inverter for Motor Drive AC and DC Servo Drive Amplifier Uninterruptible Power Supply Industrial machines, such as Welding machines



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings (at T_c=25°C unless otherwise specified)

Items		Symbols	Conditions	Conditions		Units	
Collector-Emitter voltage		Vces		,	1200	V	
Gate-Emitter voltage		V _{GES}			±20	V	
Collector current		Ic	Continuous	Tc=100°C	150		
		I _{C pulse}	1ms		300	Α	
		-Ic		1ms		A	
		-I _{C pulse}	1ms				
Collector power dissipation		Pc	1 device	1 device		W	
Junction temperature		T _j			175		
Operating junction temperature (under switching conditions)		T _{jop}			150	°C	
Case temperature		Tc			125	·	
Storage temperature		T _{stg}					
Isolation voltage between terminal and copper base (*1)		Viso	AC: 1min.		2500	VAC	
Screw torque	Mounting (*2)	-			5.0	N m	
	Terminals (*3)	-			5.0	IN III	

Note *1: All terminals should be connected together when isolation test will be done.

Note *2: Recommendable Value : 3.0-5.0 Nm (M5 or M6) Note *3: Recommendable Value : 2.5-3.5 Nm (M5)

● Electrical characteristics (at T_j= 25°C unless otherwise specified)

Items	Symbols	Conditions		Characteristics			Units
items	Symbols			min.	typ.	max.	Units
Zero gate voltage collector current	Ices	V _{GE} = 0V, V _{CE} = 1200V		-	-	1.0	mA
Gate-Emitter leakage current IGES VCE = 0V, VGE		$V_{CE} = 0V$, $V_{GE} = \pm 20V$	V _{GE} = ±20V		-	200	nA
Gate-Emitter threshold voltage	V _{GE (th)}	$V_{CE} = 20V, I_{C} = 150mA$		6.0	6.5	7.0	V
	V	V _{GE} = 15V	T _j =25°C	-	2.05	2.50	V
	V _{CE (sat)} (terminal)	Ic = 150A	T _j =125°C	-	2.35	-	
Collector Emitter acturation valtage			T _j =150°C		2.40		
Collector-Emitter saturation voltage	V _{CE (sat)} (chip)	V _{GE} = 15V I _C = 150A	T _j =25°C	-	1.75	2.20	
			T _j =125°C	-	2.05	-	
			T _j =150°C		2.10		
Internal gate resistance	R _G (int)	-		-	5	-	Ω
Input capacitance	Cies	$V_{CE} = 10V, V_{GE} = 0V, f = 1MHz$		-	12.6	-	nF
	ton	Vcc = 600V Ls = 30nH Ic = 150A Vge = ±15V		-	600	-	nsec
Turn-on time	tr			-	200	-	
	t _{r (i)}			-	50	-	
Turn-off time	toff	$R_G = 1.1\Omega$		-	600	-	
Turn-on time	tr	T _j = 150°C		-	40	-	
	VF	V _{GE} = 0V I _F = 150A	T _j =25°C	-	1.85	2.30	
	(terminal)		T _j =125°C	-	2,00	-	
Forward on voltage	(terrillial)		T _j =150°C		1.95		
Forward on voltage	VF	V _{GE} = 0V	T _j =25°C	-	1.70	2.15	
	1	V _{GE} = 0V I _F = 150A	T _j =125°C	-	1.85	-	
	(chip)	IF - TOUA	T _j =150°C		1.80		
Reverse recovery time	trr	I _E = 150A		-	150	_	nsec

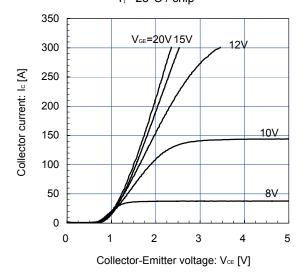
Thermal resistance characteristics

Items	Symbols	Conditions	Characteristics			Units
items		Conditions	min.	typ.	max.	Ullits
Thermal resistance (Aderrica)	Ь	IGBT	-	-	0.19	°C/W
Thermal resistance (1device)	R _{th(j-c)}	FWD	-	-	0.31	
Contact thermal resistance (1device) (*4)	R _{th(c-f)}	with Thermal Compound	-	0.050	-	

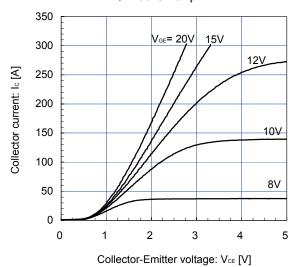
Note *4: This is the value which is defined mounting on the additional cooling fin with thermal compound.

■ Characteristics (Representative)

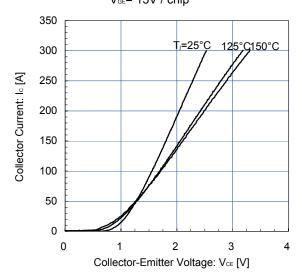
Collector current vs. Collector-Emitter voltage (typ.) T_i = 25°C / chip



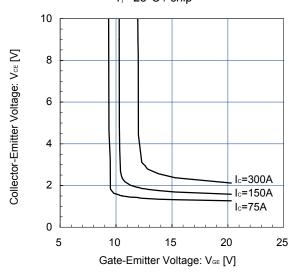
Collector current vs. Collector-Emitter voltage (typ.) T_i = 150°C / chip



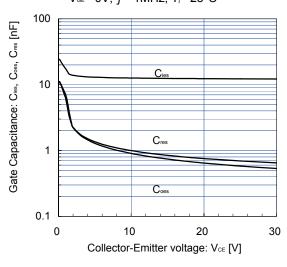
Collector current vs. Collector-Emitter voltage (typ.) V_{GE} = 15V / chip



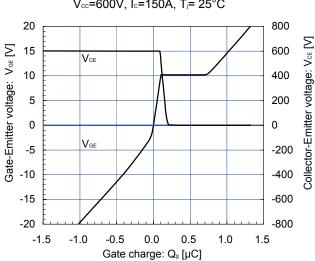
Collector-Emitter voltage vs. Gate-Emitter voltage T_j= 25°C / chip

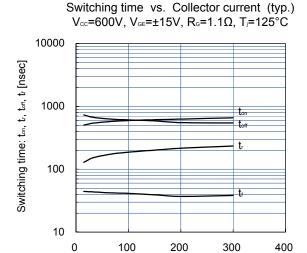


Gate Capacitance vs. Collector-Emitter Voltage V_{GE} = 0V, f= 1MHz, T_{J} = 25°C

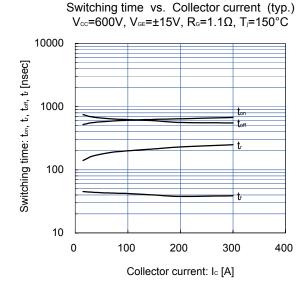


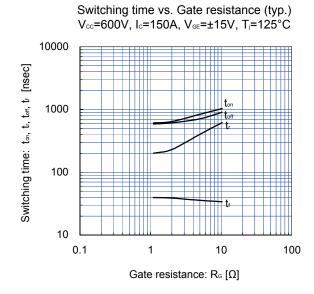
Dynamic Gate Charge (typ.) V_{cc}=600V, I_c=150A, T_i= 25°C

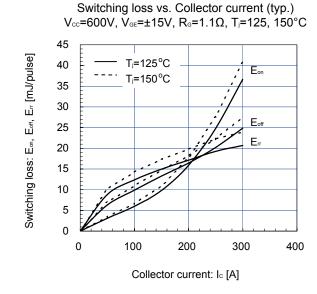


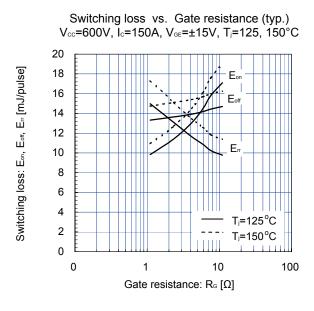


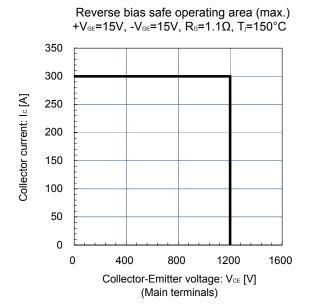
Collector current: Ic [A]



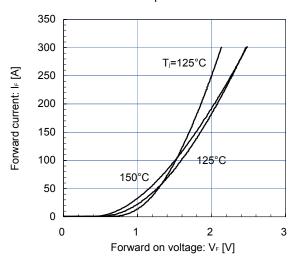




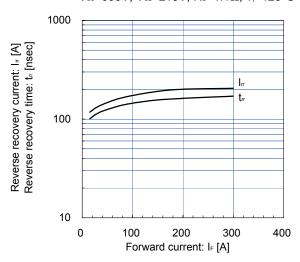




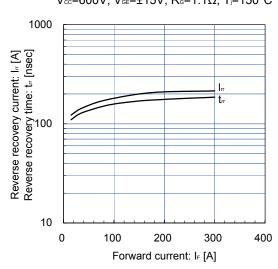
Forward Current vs. Forward Voltage (typ.) chip



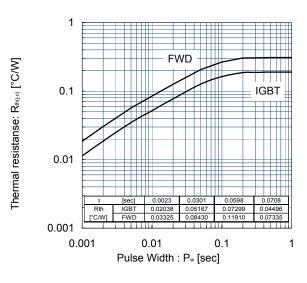
Reverse Recovery Characteristics (typ.) V_{CC} =600V, V_{GE} =±15V, R_{G} =1.1 Ω , T_{J} =125°C



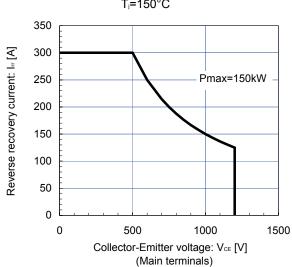
Reverse Recovery Characteristics (typ.) V_{cc} =600V, V_{ce} =±15V, R_{c} =1.1 Ω , T_{j} =150°C



Transient Thermal Resistance (max.)

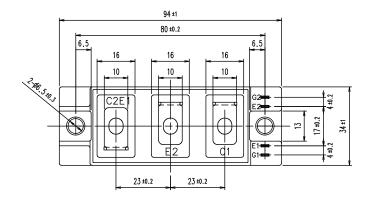


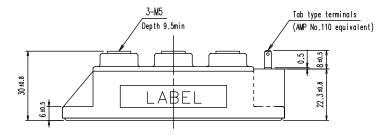
FWD safe operating area (max.) T=150°C



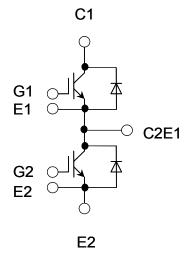
http://www.fujielectric.com/products/semiconductor/

■ Outline Drawings, mm





■ Equivalent Circuit Schematic



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